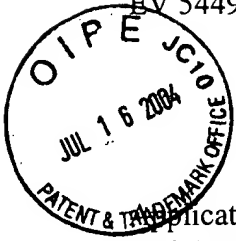


EV 544918909 US

INF 4384  
PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Lee et al.

Serial No. 09/980,222

Filed 4/19/2002

Confirmation No. 1305

For A METHOD OF ASSEMBLING A SEMICONDUCTOR DEVICE PACKAGE

July 16, 2004

TO THE COMMISSIONER OF PATENTS

SIR:

**INFORMATION DISCLOSURE STATEMENT**

\* In accordance with 37 C.F.R. 1.97 and 1.98 and MPEP 609, and in compliance with the duty of disclosure set forth in 37 C.F.R. 1.56, applicants submit the attached PTO/SB/08A for consideration by the Patent and Trademark Office in the above-entitled application and to be made of record therein. In accordance with the OG notice of August 5, 2003 partially waiving the requirements of 37 C.F.R. 1.98(a)(2)(i), copies of the U.S. patent documents are not supplied. Applicants submit herewith copies of the literature references.

The Commissioner is hereby authorized to charge \$180 to cover the fee specified in 37 CFR §1.17(p) for submission of this Information Disclosure Statement to Deposit Account No. 19-1345.


Respectfully submitted,

Robert M. Bain, Reg. No. 36,736  
SENNIGER, POWERS, LEAVITT & ROEDEL  
One Metropolitan Square, 16th Floor  
St. Louis, Missouri 63102  
(314) 231-5400

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02 FC:1806 180.00 DA

RMB/ROE/cjl

PTO/SB/08A <b>SUPPLEMENTAL  INFORMATION DISCLOSURE  STATEMENT BY APPLICANT</b>  (Use as many sheets as necessary)				<b>Complete if Known</b>	
				Application Number	09/980,222
				Filing Date	November 29, 2001
				Confirmation Number	1305
				First Named Inventor	Charles Lee
				Group Art Unit	2318
				Examiner Name	A. Roman
Sheet	1	of	2	Attorney Docket No.	INF 4384

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code <sup>2</sup> (if known)		
	5	5,002,968		Lin et al.	06/11/1991
	6	5,098,796		Lin et al.	03/24/1992
	7	5,230,932		Chen et al.	07/27/1993
	8	5,250,363		Chen	10/05/1993
	9	5,573,845		Parthasarathi	11/12/1996
OTHER ART - NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.) date, page(s), volume-issue number(s), publisher, city and/or country where published.			T <sup>6</sup>
	10	LEE et al., An Analytical Characterization and Reliability Testing of an Adhesion Enhancing Zn-Cr Leadframe Coating for Popcorn Prevention, 1998 Electronic Components and Technology Conference, 6/98, 1154-1161			
	11	LEE et al., Investigation of a Novel Leadframe Treatment for "Dry-Pack Free" Packaging, 1997 Electronic Components and Technology Conference, 1997, 1049-1060			
	12	PARTHASARATHI et al., Leadframe Treatment to Prevent Delamination in Plastic Packages, 1995 IEPS Conference, 643-650			

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached or place an "A" here if English language abstract is attached..

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